MBN800H45E2-H

Silicon N-channel IGBT 4500V E2 version

FEATURES

- Low switching loss IGBT module.
- Low noise due to ultra soft fast recovery diode.
- High reliability, high durability module.
- High thermal fatigue durability.
  (delta Tc=70°C, N>30,000cycles)
- Isolated heat sink (terminal to base).

ABSOLUTE MAXIMUM RATINGS (T_C=25ºC)

Item		Symbol	Unit	MBN800H45H-H
Collector Emitter Voltage		V_{CES}	V	4,500
Gate Emitter Voltage		V_{GES}	V	±20
Collector Current	DC	I_C	A	800 (Tc=80 ºC)
	1ms	I_{CRM}		1,600
Forward Current	DC	I_F	A	800
	1ms	I_{FRM}		1,600
Operating Junction Temperature		$T_{vj\ op}$	ºC	-40 ~ +125
Maximum Junction Temperature (1)		$T_{vj\ max}$	ºC	150
Storage Temperature		T_{stg}	ºC	-50 ~ +125 (2)
Isolation Voltage		V_{ISO}	V_{RMS}	10,200(AC 1 minute)
Screw Torque	Terminals (M4/M8)	-	N·m	2/10 (3)
	Mounting (M6)	-		6 (4)

Notes: (1) Regarding the condition of Tvj max for each operation mode, please refer to LD-ES-130737.
(2) Terminal temperature shall not exceed the specified temperature in any operation.
(3) Recommended Value 1.8±0.2/9±1N·m (4) Recommended Value 5.5±0.5N·m

ELECTRICAL CHARACTERISTICS

Item		Symbol	Unit	Min.	Typ.	Max.	Test Conditions
Collector Emitter Cut-Off Current		I_{CES}	mA	-	-	17	V_{CE}=4,500V, V_{GE}=0V, T_{vj}=25ºC
				-	17	67	V_{CE}=4,500V, V_{GE}=0V, T_{vj}=125ºC
Gate Emitter Leakage Current		I_{GES}	nA	-500	-	+500	V_{GE}=±20V, V_{CE}=0V, T_{vj}=25ºC
Collector Emitter Saturation Voltage		V_{CEsat}	V	3.5	4.2	4.7	I_C=800A, V_{GE}=15V, T_{vj}=125ºC
Gate Emitter Threshold Voltage		$V_{GE(th)}$	V	5.4	6.4	7.4	V_{CE}=10V, I_C=800mA, T_{vj}=25ºC
Input Capacitance		C_{ies}	nF	-	110	-	V_{CE}=10V, V_{GE}=0V, f=100kHz, T_{vj}=25ºC
Internal Gate Resistance		$R_{G(int)}$	Ω	-	1.2	-	V_{CE}=10V, V_{GE}=0V, f=100kHz, T_{vj}=25ºC
Turn On Delay Time		$t_{d(on)}$	μs	-	0.6	-	V_{CC}=2,600V, I_C=800A
Rise Time		t_r		1.0	2.1	4.2	L_S=165nH
Turn Off Delay Time		$t_{d(off)}$		-	2.4	-	R_G=4.7Ω (5)
Fall Time		t_f		1.2	2.4	3.6	V_{GE}=±15V, T_{vj}=125ºC
Forward Voltage Drop		V_F	V	3.0	3.7	4.2	I_F=800A, V_{GE}=0V, T_{vj}=125ºC
Reverse Recovery Time		t_{rr}	μs	0.3	0.7	1.4	V_{CC}=2,600V, I_F=800A, L_S=165nH T_{vj}=125ºC
Turn On Loss		$E_{on(10\%)}$	J/P	-	2.1	3.2	V_{CC}=2,600V, I_C=IF=800A, L_S=165nH R_G=4.7Ω (5) V_{GE}=±15V, T_{vj}=125ºC
		$E_{on(full)}$		-	2.5	-	
Turn Off Loss		$E_{off(10\%)}$	J/P	-	2.1	3.2	
		$E_{off(full)}$		-	2.5	-	
Reverse Recovery Loss		$E_{rr(10\%)}$	J/P	-	1.7	2.5	
		$E_{rr(full)}$		-	1.9	-	
Partial discharge extinction voltage		V_e	V_{RMS}	3,500	-	-	f=50Hz, Q_{PD}≤10pC(acc. to IEC 61287)
Stray inductance module		L_{SCE}	nH	-	21	-	
Thermal Impedance	IGBT	$R_{th(j-c)}$	K/W	-	-	0.013	Junction to case
	FWD	$R_{th(j-c)}$		-	-	0.026	
Contact Thermal Impedance		$R_{th(c-f)}$	K/W	-	0.007	-	Case to fin (λgrease=1W/(m·K), heat-sink flatness ≤50um)

Notes: (5) R_G value is a test condition value for evaluation, not recommended value.
Please, determine the suitable R_G value by measuring switching behaviors.

* Please contact our representatives at order.
* For improvement, specifications are subject to change without notice.
* For actual application, please confirm this spec sheet is the newest revision.

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DEFINITION OF TEST CIRCUIT

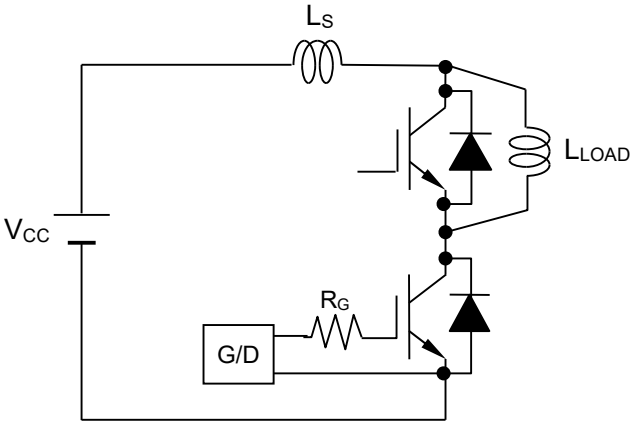
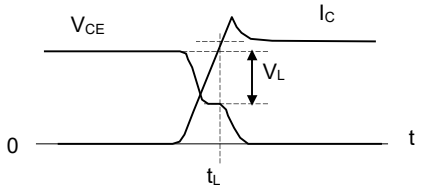
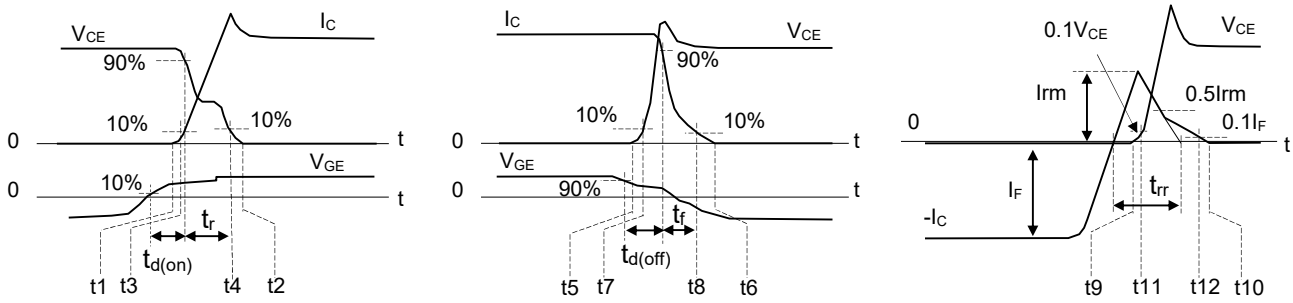


Fig.1 Switching test circuit



$$L_S = \frac{V_L}{\left(\frac{dI_C}{dt}\right)_{t=t_L}}$$

Fig.2 Definition of stray inductance



$$E_{on(10\%)} = \int_{t3}^{t4} I_C \cdot V_{CE}\, dt \qquad E_{off(10\%)} = \int_{t7}^{t8} I_C \cdot V_{CE}\, dt \qquad E_{rr(10\%)} = \int_{t11}^{t12} I_F \cdot V_{CE}\, dt$$

$$E_{on(Full)} = \int_{t1}^{t2} I_C \cdot V_{CE}\, dt \qquad E_{off(Full)} = \int_{t5}^{t6} I_C \cdot V_{CE}\, dt \qquad E_{rr(Full)} = \int_{t9}^{t10} I_F \cdot V_{CE}\, dt$$

Fig.3 Definition of switching loss

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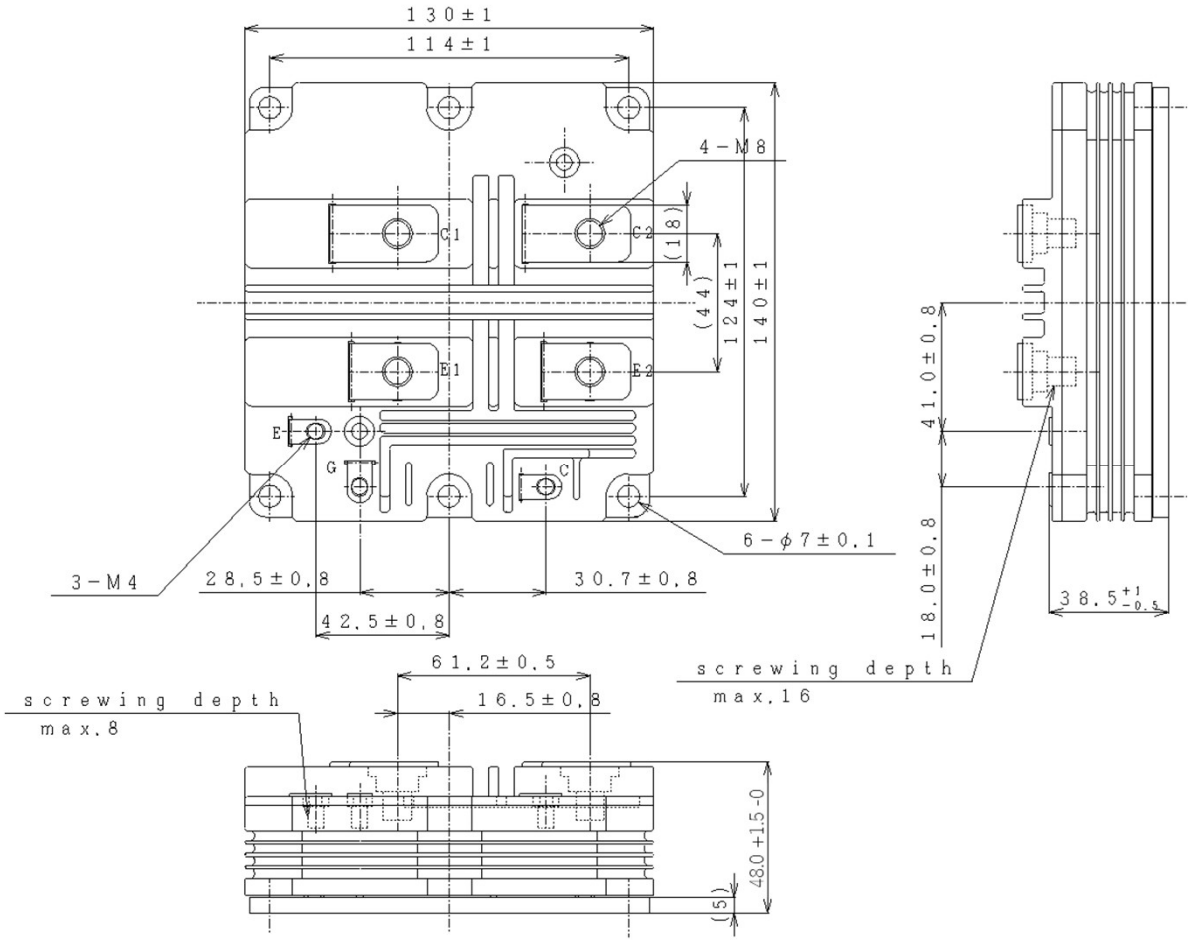
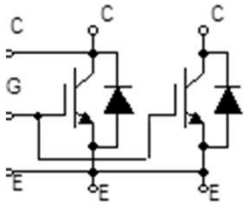
OUTLINE DRAWING

Unit in mm



Weight: 1,050g

CIRCUIT DIAGRAM



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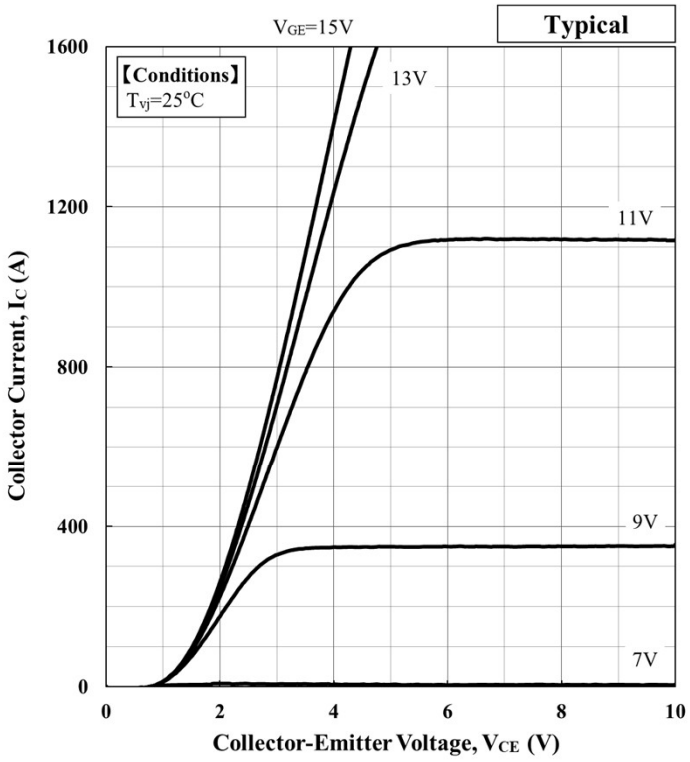
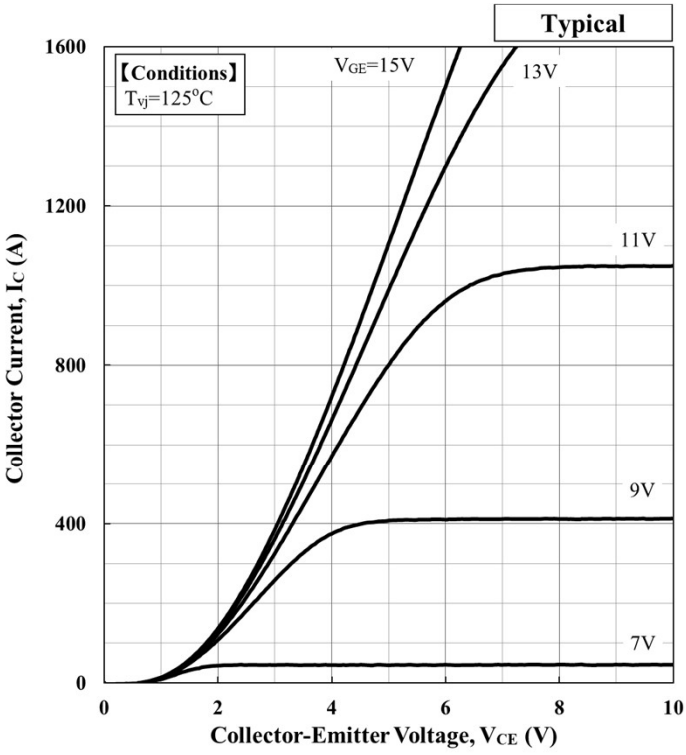


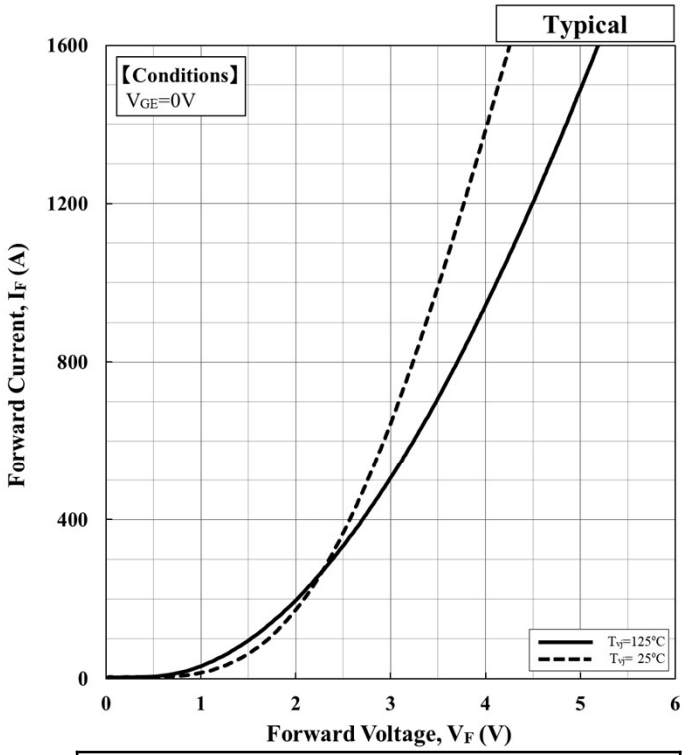
$V_{CE}(sat)[V] = a_3 \cdot \lvert I_c \rvert^3 + a_2 \cdot \lvert I_c \rvert^2 + a_1 \cdot \lvert I_c \rvert + a_0$					
Temp.[°C]	V_{GE}[V]	a_3	a_2	a_1	a_0
25	15	3.23E-10	-1.22E-06	3.01E-03	1.27E+00

Collector Current vs. Collector Emitter Voltage



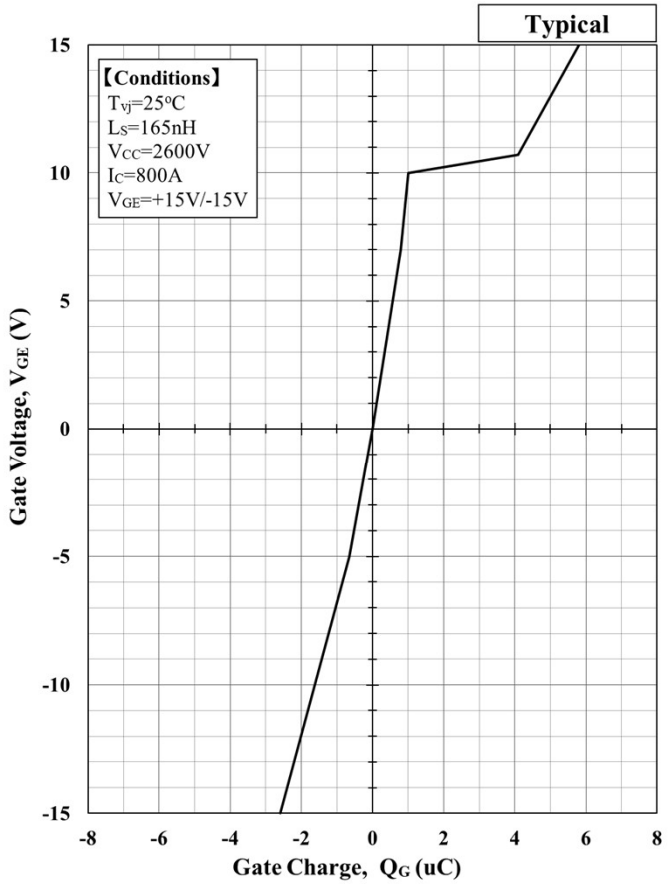
$V_{CE}(sat)[V] = a_3 \cdot \lvert I_c \rvert^3 + a_2 \cdot \lvert I_c \rvert^2 + a_1 \cdot \lvert I_c \rvert + a_0$					
Temp.[°C]	V_{GE}[V]	a_3	a_2	a_1	a_0
125	15	6.22E-10	-2.13E-06	4.86E-03	1.38E+00

Collector Current vs. Collector Emitter Voltage



$V_F[V] = a_3 \cdot \lvert I_F \rvert^3 + a_2 \cdot \lvert I_F \rvert^2 + a_1 \cdot \lvert I_F \rvert + a_0$				
Temp.[°C]	a_3	a_2	a_1	a_0
25	5.77E-10	-2.01E-06	3.51E-03	1.43E+00
125	6.66E-10	-2.46E-06	4.79E-03	1.12E+00

Forward Voltage of free-wheeling diode



V_{GE}-Q_G curve

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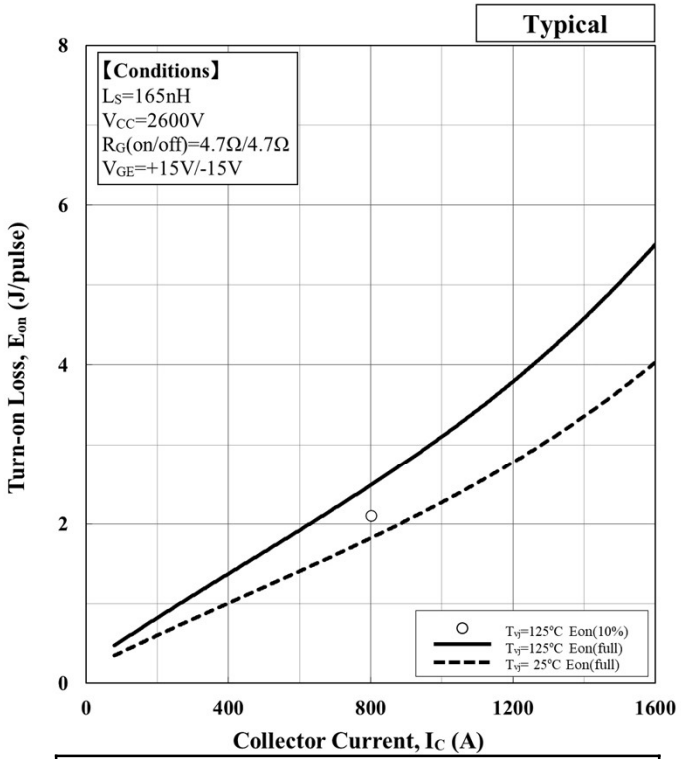
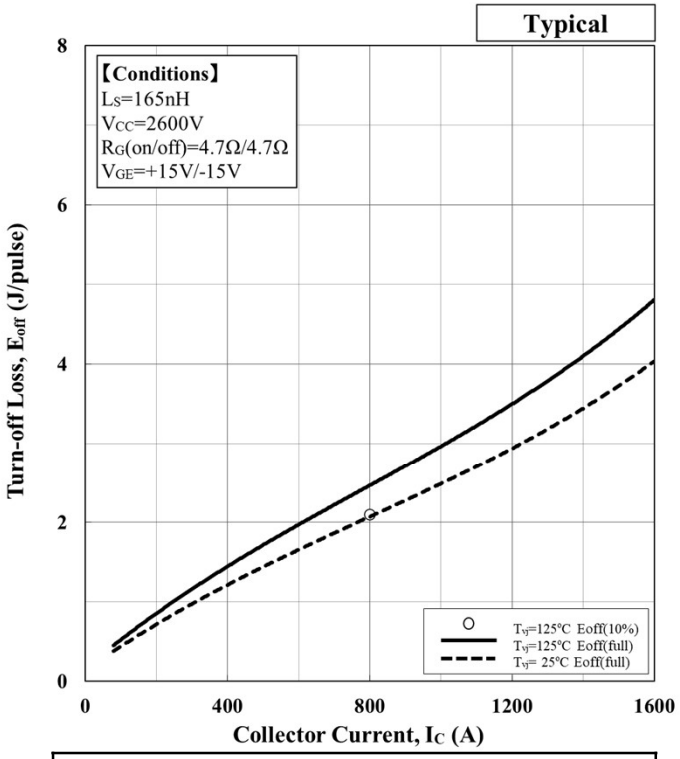


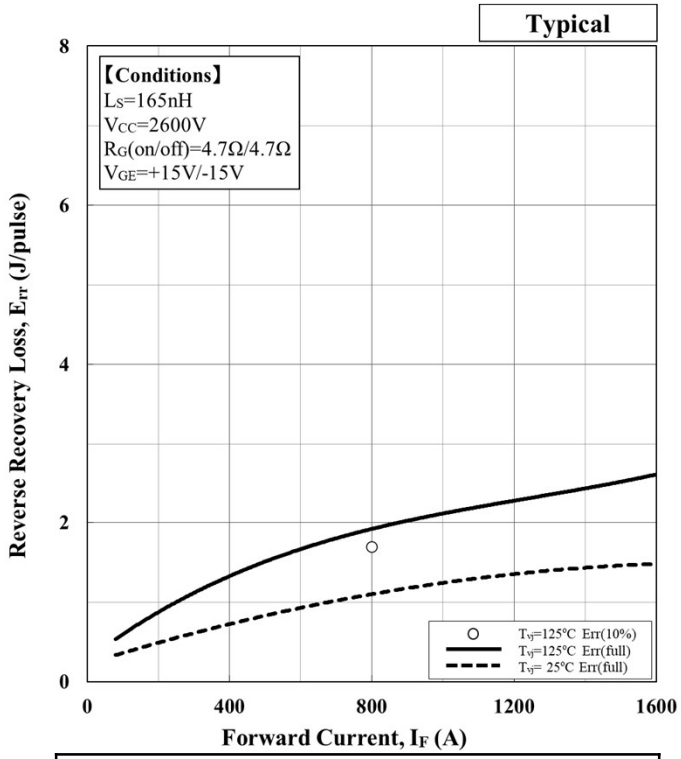
$E\,[J] = a_3 \cdot \lvert I_c \rvert^3 + a_2 \cdot \lvert I_c \rvert^2 + a_1 \cdot \lvert I_c \rvert + a_0$				
Temp.[°C]	a_3	a_2	a_1	a_0
25	4.21E-10	-5.69E-07	2.25E-03	1.70E-01
125	5.75E-10	-7.78E-07	3.07E-03	2.33E-01

Turn-on loss vs. Collector current



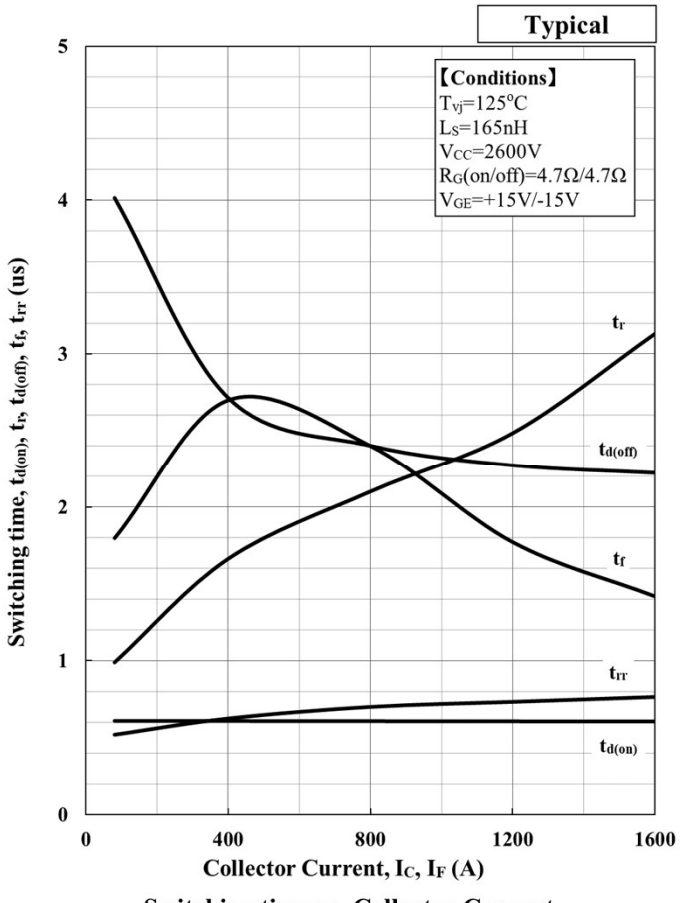
$E\,[J] = a_3 \cdot \lvert I_c \rvert^3 + a_2 \cdot \lvert I_c \rvert^2 + a_1 \cdot \lvert I_c \rvert + a_0$				
Temp.[°C]	a_3	a_2	a_1	a_0
25	5.89E-10	-1.39E-06	3.15E-03	1.37E-01
125	7.02E-10	-1.66E-06	3.76E-03	1.64E-01

Turn-off loss vs. Collector current



$E\,[J] = a_3 \cdot \lvert I_F \rvert^3 + a_2 \cdot \lvert I_F \rvert^2 + a_1 \cdot \lvert I_F \rvert + a_0$				
Temp.[°C]	a_3	a_2	a_1	a_0
25	-	-3.88E-07	1.41E-03	2.23E-01
125	5.57E-10	-2.08E-06	3.36E-03	2.81E-01

Recovery loss vs. Forward current



Switching time vs. Collector Current

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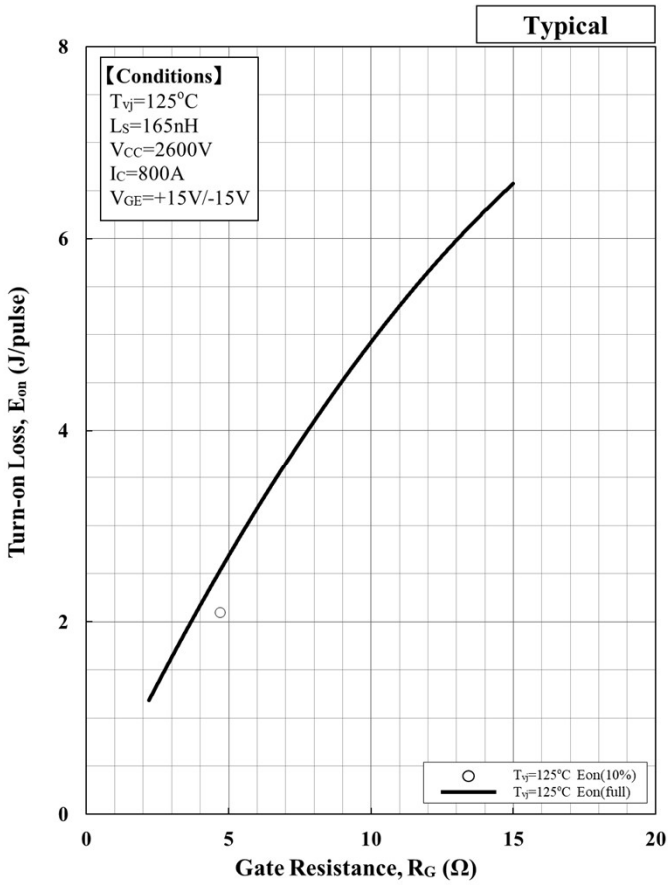
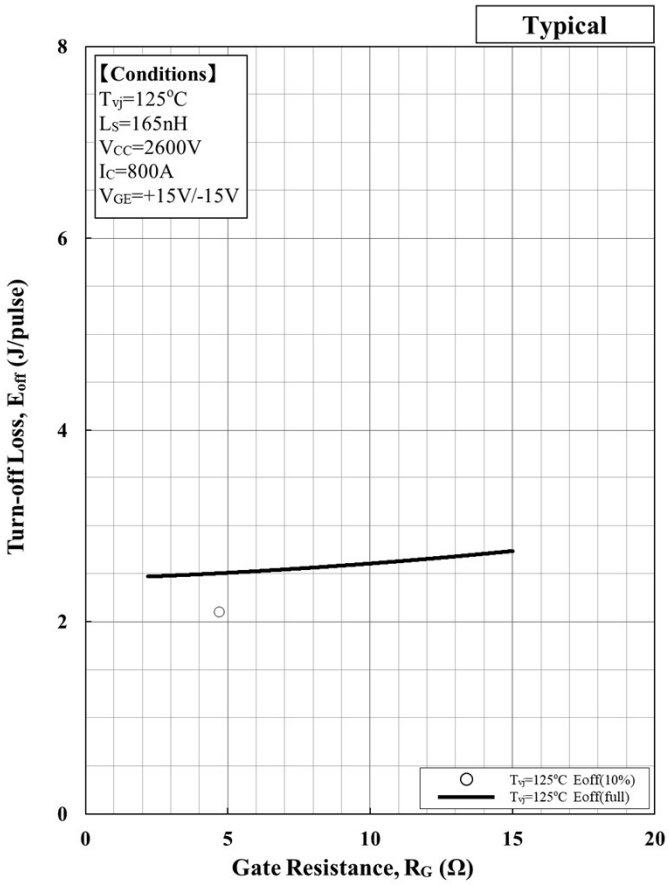
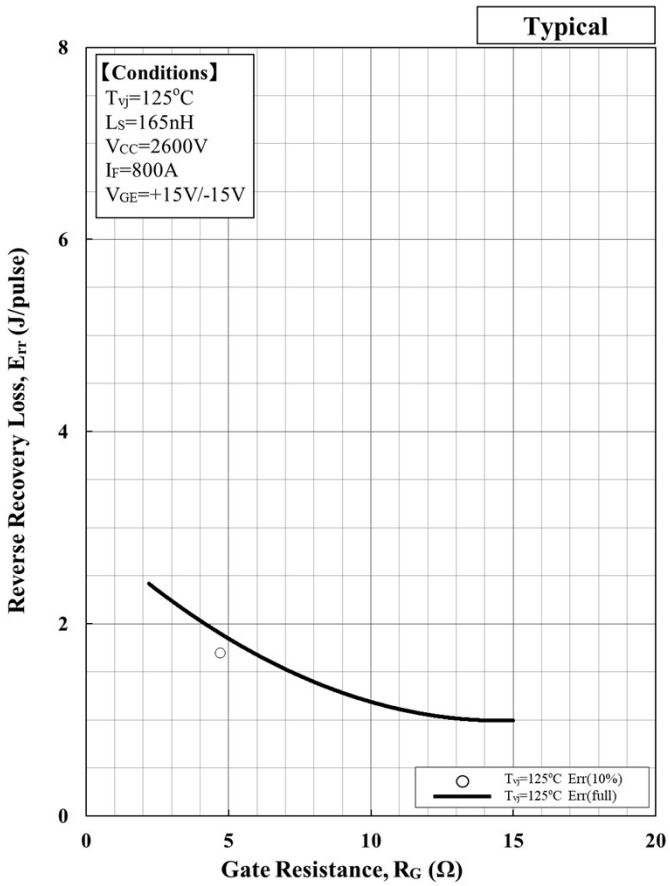


Turn-on loss vs. Gate Resistance



Turn-off loss vs. Gate Resistance



Reverse Recovery loss vs. Gate Resistance

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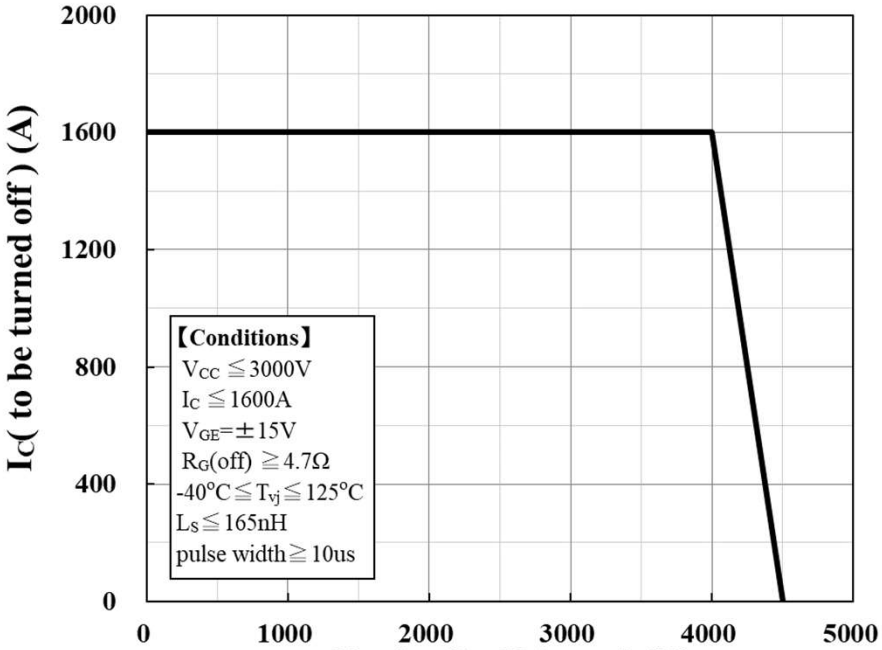
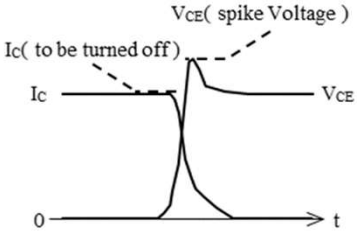
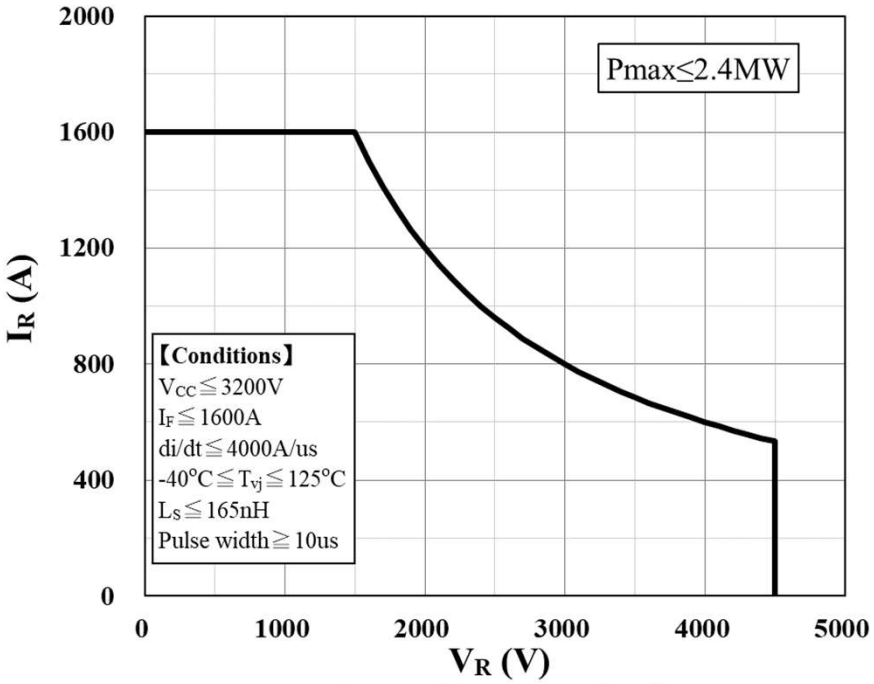


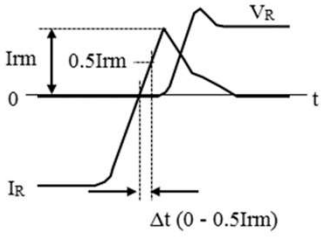
Reverse Bias Safe Operation Area (RBSOA)



Definition of RBSOA waveform



Reverse Recovery Safe Operation Area (RRSOA)



$$di/dt = \frac{0.5Irm}{\Delta t}$$

Definition of Recovery di/dt

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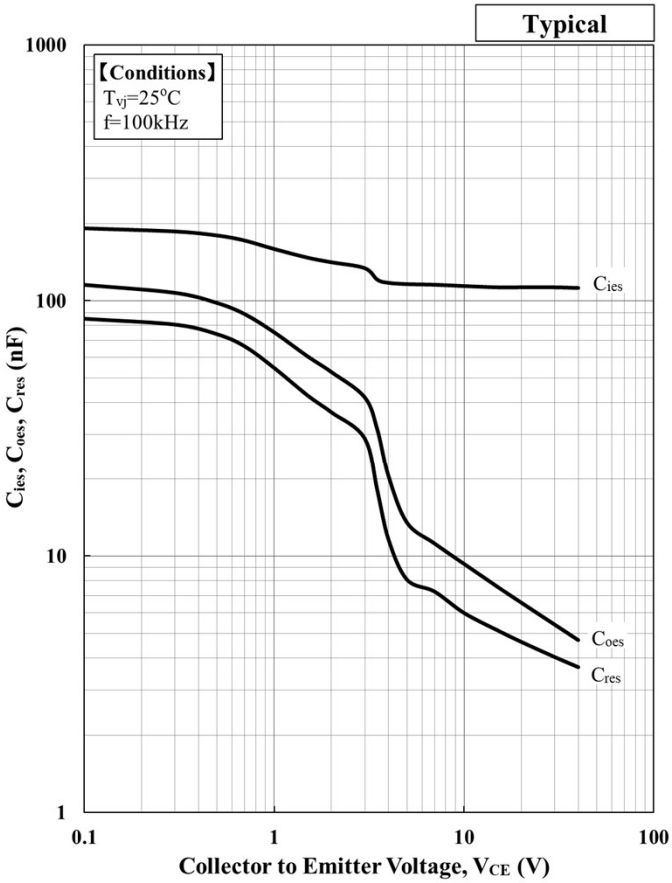
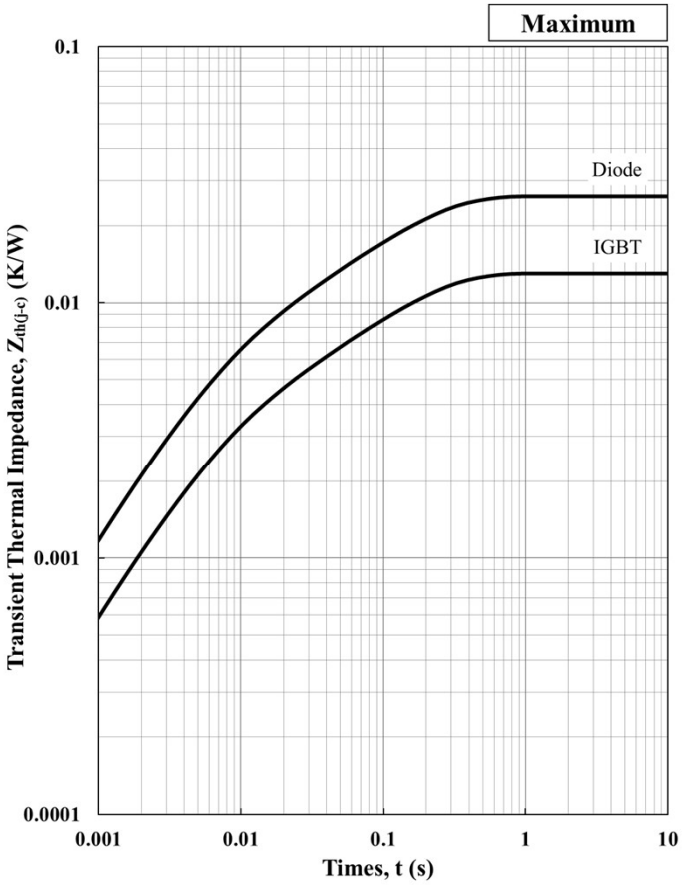


Capacitance vs. Collector to Emitter Voltage



Transient Thermal Impedance Curve

Foster model lumped circuit constant

n	1	2	3	4	Unit
R th, IGBT [n]	8.05E-03	2.47E-03	2.39E-03	1.31E-04	[K/W]
C th, IGBT [n]	2.03E+01	1.09E+01	2.56E+00	6.55E+00	[J/K]
R th, Diode [n]	1.61E-02	4.91E-03	4.76E-03	2.61E-04	[K/W]
C th, Diode [n]	1.02E+01	5.51E+00	1.28E+00	3.29E+00	[J/K]

Cauer model lumped circuit constant

n	1	2	3	4	Unit
R th, IGBT [n]	1.91E-03	2.61E-03	4.04E-03	4.48E-03	[K/W]
C th, IGBT [n]	1.46E+00	9.96E-01	8.00E+00	2.21E+01	[J/K]
R th, Diode [n]	3.81E-03	5.20E-03	8.04E-03	8.93E-03	[K/W]
C th, Diode [n]	7.34E-01	5.00E-01	4.02E+00	1.11E+01	[J/K]

Material declaration

Please note the following materials are contained in the product,
in order to keep characteristic and reliability level.

Material	Contained part
Lead (Pb) and its compounds	Solder

MBN800H45E2-H

Minebea POWER SEMICONDUCTORS

Notices

1. Since mishandling of semiconductor devices may cause malfunctions, please be sure to read "Precautions for Safe Use and Notices" in the individual brochure before use.
2. When designing an electronic circuit using semiconductor devices, please do not exceed the absolute maximum rating specified for the device under any external fluctuations. And for pulse applications, please also do not exceed the "Safe Operating Area (SOA)".
3. Semiconductor devices may sometimes break down by accidental or unexpected surge voltage, so please be careful about the safety design such as redundant design and malfunction prevention design which don't cause the damage expand even if they break down.
4. In cases where extremely high reliability is required (such as use in nuclear power control, aerospace and aviation, traffic equipment, life-support-related medical equipment, fuel control equipment and various kinds of safety equipment), safety should be ensured by using semiconductor devices that feature assured safety or by means of users' fail-safe precautions or other arrangement. Or consult with MPSD's sales department staff. (When semiconductor devices fail, as a result the semiconductor devices or wiring, wiring pattern may smoke, ignite, or the semiconductor devices themselves may burst.)
5. A semi-processed article is done now using solder which contains lead inside the semiconductor devices. There is possibility of the regulation substance depend on the applied models, so please check before using.
6. This specification is a material for component selection, which describes specifications of power semiconductor devices (hereinafter referred to as products), characteristic charts, and external dimension drawings.
7. The information given herein, including the specifications and dimensions, is subject to change without prior notice to improve product characteristics. Before ordering, purchasers are advised to contact with Minebea power semiconductor sales department for the latest version of this data sheets.
8. For handling other than described in this manual, follow the handling instructions (IGBT-HI-00002).

■ For inquiries relating to the products, please contact nearest representatives that is located "Inquiry" portion on the top page of a home page.

Minebea power semiconductor home page address
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URL : https://www.minebea-psd.com/

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Minebea POWER SEMICONDUCTORS

Usage

1. MPSD warrants that the MPSD products have the specified performance according to the respective specifications at the time of its sale. Testing and other quality control techniques of the MPSD products by MPSD are utilized to the extent MPSD needs to meet the specifications described in this document. Not every device of the MPSD products is specifically tested on all parameters, except those mandated by relevant laws and/or regulations.
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